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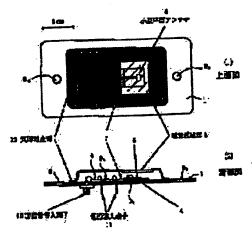
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(54) SEMICONDUCTOR MODULE INCORPORATED WITH ANTENNA ELEMENT

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor module incorporated with an antenna element suitable for milimeter waves and quasi milimeter waves by providing a means for airtightly sealing the antenna element, an amplifier circuit and a frequency conversion circuit formed on the substrate in common space.

SOLUTION: An antenna element 5 is formed on a dielectric substrate 4 oppositely to an electromagnetic wave transmitting window 2 formed on a seal cover. A plane antenna such as patch antenna and a slot antenna is us d for the element 5. Semiconductor integrated circuits 6, 7 on which a microwave circuit and a milimeter-wave or quasi milimeter wave circuit constituted of an amplifier circuit and a frequency conversion circuit are respective integrated are formed on another semiconductor substrate different from the substrate 4. The substrate and the substrate 4 are arranged on one common side a substrate 1. The seal cover consisting of a conductive material is welded or screwed with/into the substrate 1 on an airtight sealing part 12 formed on its peripheral part so as to be stuck to the substrate 1 to airtightly seal the substrate 1.



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